2015 Spring CS 210001 Circuits and Electronics (I) Midterm I

Class: 10206212 ID:

Part One: Calculation (80%) $E_g = 1.1 \text{ eV for Si}, B = 5.23 \times 10^{15} \text{ cm}^{-3} \text{ K}^{-3/2} \text{ for Si}, k = 86 \times 10^{-6} \text{eVK}^{-1}$ $u_n = 1350cm^2V^{-1}S^{-1}$, $u_p = 480cm^2V^{-1}S^{-1}$, $ni(T) = BT^{\frac{2}{2}}e^{(-Eg/2kT)}$

- 1. (11%) The electron concentration in silicon at $T = 300 \,\mathrm{K}$ is $n_0 = 2 \times 10^4 \,\mathrm{cm}^{-3}$. (a)(4%) Determine the hole concentration. (b)(2%) Is the material n-type or p-type? (c)(2%) What might be the impurity? (d)(3%) What is the conductivity σ of this material?
- 2. (10%) Ohm's Law can be expressed as $J = \sigma \times E$. Prove that this is held for a semiconductor where $\sigma = qnu_n + qpu_p, q$ is charge, n is electron concentration, p is hole concentration, u_n is the electron mobility, u_p is the hole mobility, J is current density, and E is electrical field.
- 3. (6%) Prove that the $Vp = \sqrt{2} Vrms$ for a sine wave $V = Vp \times \sin\theta$ where Vp is peak value and Vrms is the effective value of signal V.
- 4. (8%) Given a diode circuit as shown in Fig. 1. Assume the diode is modeled as V, in series with a forward diode resistance rf when the diode is forward biased. Show that the V_D can be expressed as $\frac{V_s \times rf + V_r \times R}{rf + R}$ when the diode is forward biased.

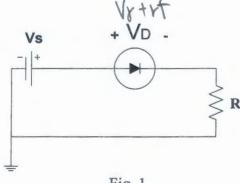


Fig. 1

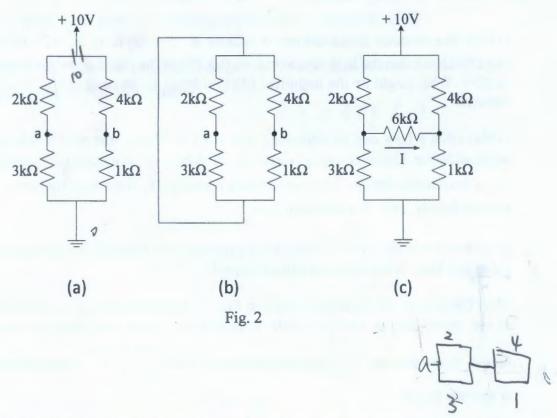
Vo=W+14. I =VS-IR 7 = Vs-Vo Vr+rf. (Vs-Vo)

5. (4%) Prove that the equivalent resistance of two parallel resistors is $(R1 \times R2)/(R1 + R2)$.

$$-R_1 - R_2 - \frac{\chi}{R} = \frac{\chi}{R_1} + \frac{\chi}{R_2}$$

$$IR = IR_1 + IR_2$$

6. (10%)(a)(3%) For the circuit in Fig. 2(a), find the voltage of node a and voltage of node b. What is the voltage Vab between node a and b? (b)(3%) Find the terminal resistance between node a and node b of Fig. 2(b), that is, Rab=? (c)(4%) Determine the current I in Fig. 2(c) by using Theorem.



7. (6%) Using the superposition theorem, solve for the current I in Fig. 3.

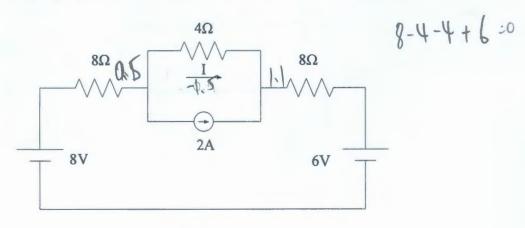
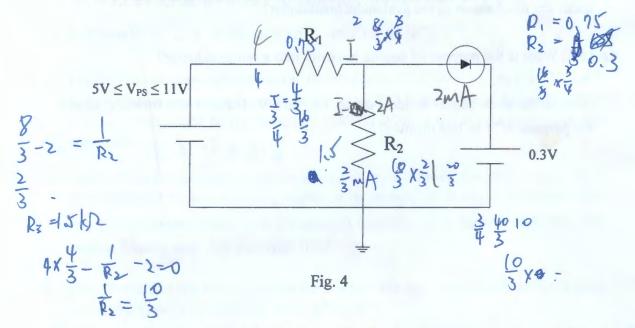
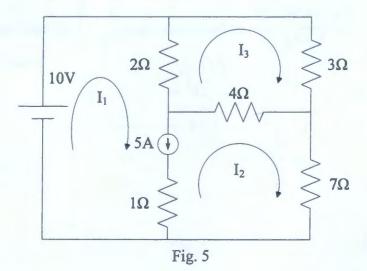


Fig. 3

- 8. (6%) Consider a silicon pn junction at 300K. n-type is doped to $N_d = 10^{17}$ cm⁻³. If the built-in potential barrier $V_{bi} = 0.712$ V, determine the p-type doping concentration.
- 9. (10%) For the circuit in Fig. 4, assume $V_{\gamma} = 0.7$ V, rf = 0 for the diode. The diode is to remain "on" for a power supply voltage in the range $5 \le V_{PS} \le 11$. The minimum diode current is 2mA and the maximum power dissipated in the diode is to be no more than 7mW. Determine the values of R1 and R2.



10. (9%) Use the mesh analysis method to solve for the currents I_1 , I_2 and I_3 in Fig. 5. You just list the equations only. Do not solve the currents explicitly.



Part Two: Answer the following question as clear as you can (20%)

- 1. (4%) Explain the mechanism of Zener breakdown.
- 2. (4%) Explain why the iteration method is useful in solving the current and voltage of a diode circuit.
- 3. (4%) Why is the breakdown voltage of a diode positive-temperature-coefficient under the mechanism of the avalanche breakdown?
- 4. (4%) What is the purpose of doping impurity into a semiconductor?
- 5. (4%) In the modeling of an ideal diode, i.e., its I-V characteristic formula, what's the purpose of -1 in this formula?

$$I = \frac{V_{c} - V_{D}}{R}$$

$$V_{D} = V_{r} + rf(\frac{V_{s} - V_{D}}{R})$$

$$V_{D} + \frac{rf}{R}V_{D} = V_{r} + \frac{rf}{R}V_{s}$$

$$V_{D} = \frac{V_{r}R + rfV_{s}}{R}$$

$$V_{D} = \frac{V_{r}R + rfV_{s}}{R} \times \frac{R}{R + rf} = \frac{V_{s} \times rf + V_{r} \times R}{R + rf}$$

$$\frac{V}{R} = \frac{V}{R_1} + \frac{V}{R_2}$$

$$\frac{1}{R} = \frac{1}{R_1} + \frac{1}{R_2} = \frac{k_1 + R_2}{R_1 \times R_2}$$

$$R = \frac{P_1 \times R_2}{R_1 + R_2} + \frac{1}{R_1 \times R_2}$$

$$\frac{1}{1000}$$
 $\frac{3}{5} = 6 = V_{a}$

(b)
$$Rab = \frac{3x^2}{5} + \frac{4x^2}{5}$$
 / $\frac{10}{5}$ / $\frac{10}{5}$ / $\frac{10}{5}$

(c)
$$I = \frac{4}{2+6} = 0.5 \text{ mA}$$

$$I_1 = \frac{8}{8+8+4} = \frac{8}{30} = \frac{2}{5} = 0.4 A$$

$$32 + 70J_2 = 0$$

$$J_2 = -\frac{3^2}{50} = -1.6A$$

$$13 = \frac{-6}{8+8+4} = \frac{-6}{20} = 0.3A$$

Vbi = 4 In March 0.7/2 = 0.026 Qu Na X1017

Vr (300) = 11600 = 0,026 Mi (300)= /JX10'0

(1.5x1010)2 = e 26

Na = (1.5 ×1010) = ×1017 × e 26 = 1.7586×1015 cm-3 1.916X101

9. min = Vps=50 ID= 2MA Vx=0.7V

$$A = 1.7586 \times 10^{-15} \text{ cm}^{-3}$$
 $A = 1.7586 \times 10^{-15} \text{ cm}^{-3}$
 $A = 1.7586 \times 10^{-15} \text{ cm}^{-3}$

6 R1-R2=2mA

00 = 8mA R1 = 0.75 FR R2=0.3KP *

10.
$$0 \frac{I_1 - I_2 = 5}{10 = (I_1 - I_3) + 5}$$

 $\Theta = \frac{3I_3 + (I_3 - I_2)_4 + (I_3 - I_1)_2 = 0}{(I_2 - I_3)_4 + I_2 + (-5)_1 \times 0}$

人因電場過大,eih 獲得足夠能量脫離產生電流

- 2. iteration method 是用逼近法一步一步向答案靠近,敲差较小能得到较精准的答案
- 3.因温度上升熱擾動增力力,碰撞其價虧建機率下降,e、ht 產生變少,故所需 breakdown voltage 上升
- 4. 因 semiconductor原本又鲁生成 10°個自由電子, ob ping impurity 後可增加動電子的數目, 以增加導電性
- 5.因可能會有遊偏的情況發生

STREET, SQUARE